

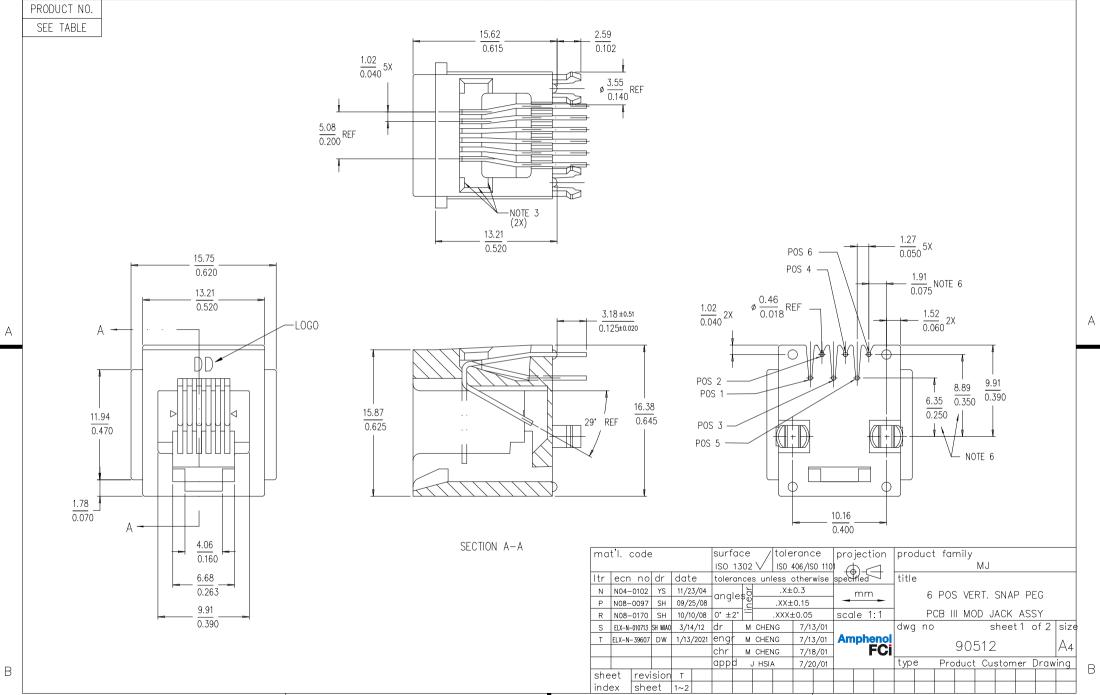
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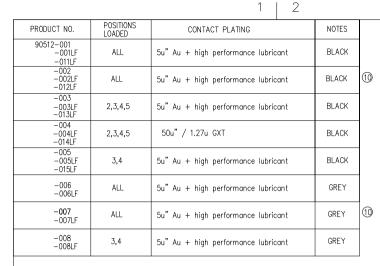
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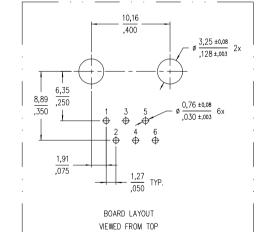
PDS: Rev :T3

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DIRECTION OF DISMOONT
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JACK DISMOUNT METHOD

DETAIL A NOTE 5

DIRECTION OF DISMOUNT

Amphenol FCi



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	PRODUCT NO.	POSITIONS LOADED	CONTACT PLATING	REMARKS								
	90512-101 -101LF -111LF	ALL	5u" Au + high performance lubricant	NOT TOOLED								
10	-102 -102LF -112LF	ALL	5u" Au + high performance lubricant	NOT TOOLED								
	-103 -103LF -113LF	2,3,4,5	5u" Au + high performance lubricant	NOT TOOLED								
	-104 -104LF -114LF	2,3,4,5	50u" / 1.27u GXT	NOT TOOLED								
	-105 -105LF -1 <u>15LF</u>											
LEAD FREE PRODUCT NO. 0: MEETS WAVE SOLDER PROCESS PRODUCT NO. 1: MEETS PIP PROCESS PRODUCT NO.												
NOTES :												
1	1 P/NO WITH DASH 0XX -NORMAL WAVE SOLDERING APPLICATION. P/NO WITH DASH 1XX -1R REFLOW APPLICATION (NOT TOOLED).											

2 PACKAGING SPEC. BUS-14-164.

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- (3) SCRATCH MARKS ACCEPTABLE ON THESE SURFACES.
- 4 JACK IS FOR 1,57/,062 THICK PCB.
- (5) SHOULD THE JACK NEED TO BE DISMOUNTED FROM THE PCB, PLS REMOVE JACK AS PER RECOMMENDED METHOD HEREIN. (DETAIL A) NIPPING THE LEGS OF THE PEG TOGETHER IS DISALLOWED, OTHERWISE LEG BREAKAGE MAY OCCUR.
- (6) THESE DIMENSIONS ARE TAKEN FROM THE TOP OF THE PEG.
- 7 THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- 8 THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60mm MINIMUM THICK CIRCUIT BOARD.
- 9 IF LF P/N PACKAGING MEETS GS-14-920 SPECIFICATION.
- (10) EQUIVALENT THICKNESS AU AND GXT PLATING HAVE SAME FUNCTION AND THEY ARE ALTERNATIVE BY THE CUSTOEMR .

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								7/2	/20/01										Draw	ing		
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index	she	et	1~2																			

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